

ABSTRACT

EPOXY RESIN COMPOSITION FOR SEMICONDUCTOR ENCAPSULANT AND
SEMICONDUCTOR DEVICE USING THE SAME

According to the present invention, an epoxy resin composition for semiconductor encapsulant including (A) an epoxy resin, (B) a curing agent, (C) an inorganic filler, and (D) a compound in which
5 a copolymer of a 1-alkene having 5 to 80 carbon atoms and maleic anhydride is esterified with an alcohol having 5 to 25 carbon atoms in the presence of a compound represented by General Formula (1), wherein R^1 in General Formula (1) is selected from the group consisting
of an alkyl group having 1 to 5 carbon atoms, a halogenated alkyl
10 group having 1 to 5 carbon atoms, and an aromatic group having 6 to 10 carbon atoms is provided.

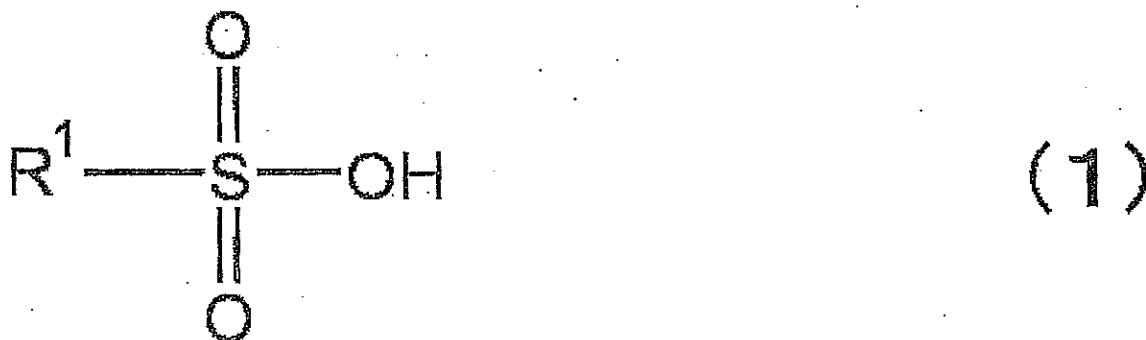


Figure 1 accompanies the abstract